

STTH8R06-Y

Automotive Turbo 2 ultrafast high voltage rectifier

Features

- Ultrafast switching
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses
- AEC-Q101 qualified

Description

The STTH8R06, which uses ST Turbo 2 600 V technology, is specially suited as a boost diode in continuous mode power factor correction and hard switching conditions. This device is also intended for use as a free wheeling diode in power supplies and other power switching applications.

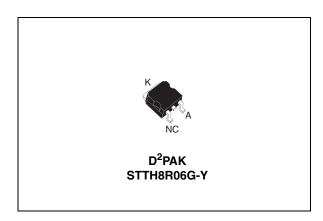


Table 1. Device summary

Symbol	Value
I _{F(AV)}	8 A
V_{RRM}	600 V
T _j	175 °C
V _F (typ)	1.5 V
t _{rr} (max)	45 ns

Characteristics STTH8R06-Y

1 Characteristics

Table 2. Absolute ratings (limiting values)

Symbol	Parameter	Value	Unit	
V _{RRM}	Repetitive peak reverse voltage	600	V	
I _{F(RMS)}	Forward rms current	40	Α	
I _{F(AV)}	Average forward current $\delta = 0.5$ $T_c = 135 ^{\circ}C$		8	Α
I _{FSM}	Surge non repetitive forward current	90	Α	
T _{stg}	Storage temperature range	-65 to + 175	°C	
Tj	Operating junction temperature range	-40 to + 175	°C	

Table 3. Thermal resistance

Symbol	Parameter	Value (max)	Unit
R _{th(j-c)}	Junction to case	1.9	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
	Payaraa laakaga aurrant	T _j = 25 °C	V - V			30	^
'R	I _R Reverse leakage current	T _j = 125 °C	$V_R = V_{RRM}$		35	400	μΑ
V _F	Forward voltage drop	T _j = 25 °C	I _F = 8 A			3.2	V
v _F Forward voilage drop	T _j = 125 °C	1 IF = 0 A		1.5	1.95	V	

To evaluate the conduction losses use the following equation:

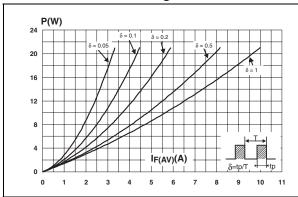
 $P = 1.35 \text{ x } I_{F(AV)} + 0.075 I_{F^{2}(RMS)}$

STTH8R06-Y Characteristics

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
			I _F = 0.5 A, I _{rr} = 0.25 A, I _R =1 A			25	
t _{rr}	Reverse recovery time	T _j = 25 °C	$I_F = 1 \text{ A},$ $dI_F/dt = -50 \text{ A/}\mu\text{s},$ $V_R = 30 \text{ V}$			45	ns
I _{RM}	Reverse recovery current				5.5	7.2	Α
S factor	Softness factor	T _j = 125 °C	$I_F = 8 \text{ A}, V_R = 400 \text{ V},$ $dI_F/dt = -200 \text{ A/}\mu\text{s}$		0.4		
Qrr	Reverse recovery charges	αιρ/αι = 2007 γ μο			150		nC
t _{fr}	Forward recovery time	I _F = 8 A,			200	ns	
V _{FP}	Forward recovery voltage	T _j = 25 °C	= 25 °C $dI_F/dt = 64 A/\mu s$ $V_{FR} = 2.5 V$			5	V

Figure 1. Average forward power dissipation Figure 2. Forward voltage drop versus versus average forward current forward current



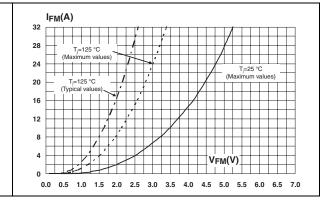
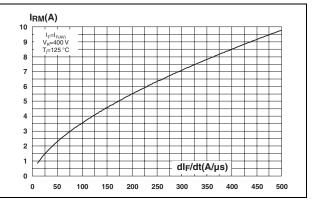


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

 $Z_{th(j-c)}/R_{th(j-c)}$ 1.0 0.9 0.8 0.7 0.6 0.5 0.3 0.2 0.1 t_p(s) 0.0 1.E-04 1.E-03 1.E-02 1.E-01 1.E+00

Figure 4. Peak reverse recovery current versus dl_F/dt (typical values)



Characteristics STTH8R06-Y

100

80

60

40

20

Figure 5. Reverse recovery time versus dl_F/dt (typical values)

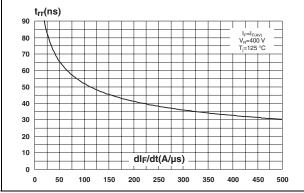
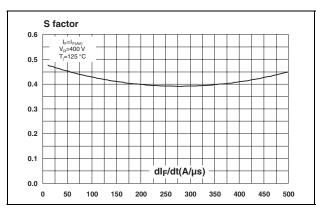
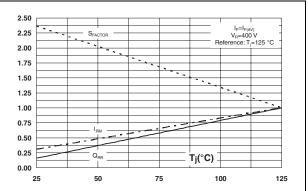


Figure 7. Reverse recovery softness factor Figure 8. Relative variations of dynamic versus dl_F/dt (typical values) parameters versus junction temperature





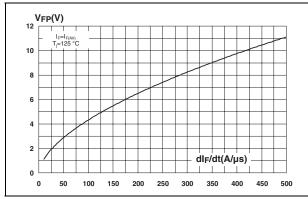
dlf/dt(A/µs)

57

STTH8R06-Y Characteristics

Figure 9. Transient peak forward voltage versus dl_F/dt (typical values)

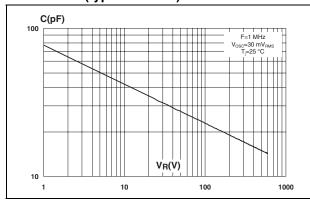
Figure 10. Forward recovery time versus dl_F/dt (typical values)

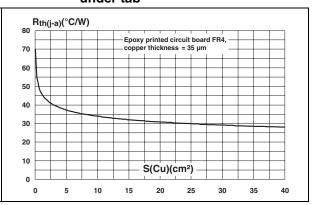


160
140
140
120
100
80
60
40
0 50 100 150 200 250 300 350 400 450 500

Figure 11. Junction capacitance versus reverse voltage applied (typical values)

Figure 12. Thermal resistance junction to ambient versus copper surface under tab



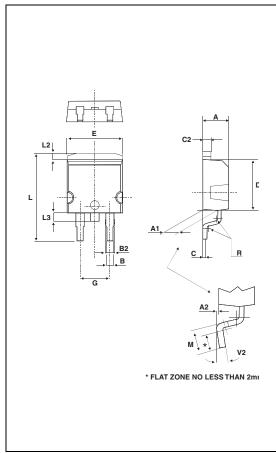


2 Package information

- Epoxy meets UL94, V0
- Lead-free package

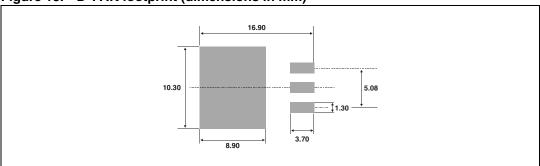
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Table 6. D²PAK dimensions



	Dimensions				
Ref.	Millimeters		Inc	hes	
	Min. Max.		Min.	Max.	
Α	4.40	4.60	0.173	0.181	
A1	2.49	2.69	0.098	0.106	
A2	0.03	0.23	0.001	0.009	
В	0.70	0.93	0.027	0.037	
B2	1.14	1.70	0.045	0.067	
С	0.45	0.60	0.017	0.024	
C2	1.23	1.36	0.048	0.054	
D	8.95	9.35	0.352	0.368	
Е	10.00	10.40	0.393	0.409	
G	4.88	5.28	0.192	0.208	
L	15.00	15.85	0.590	0.624	
L2	1.27	1.40	0.050	0.055	
L3	1.40	1.75	0.055	0.069	
М	2.40	3.20	0.094	0.126	
R	0.40 typ.		0.016	6 typ.	
V2	0°	8°	0°	8°	

Figure 13. D²PAK footprint (dimensions in mm)



3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH8R06GY-TR	STTH8R06GY	D ² PAK	1.48 g	1000	Tape and reel

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
03-Nov-2011	1	Initial release.

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8/8 Doc ID 022291 Rev 1